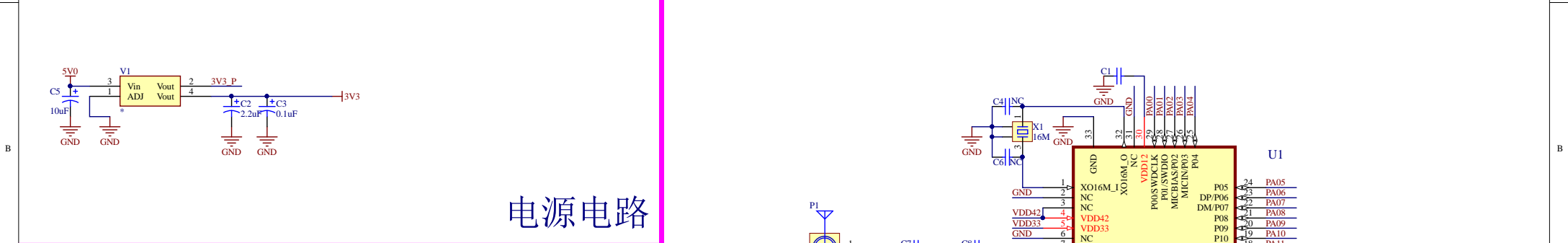
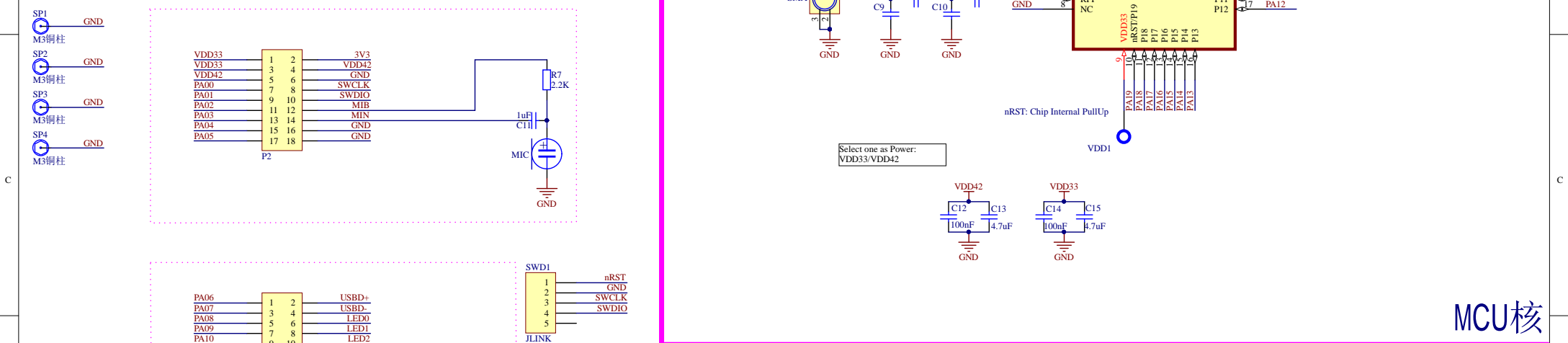


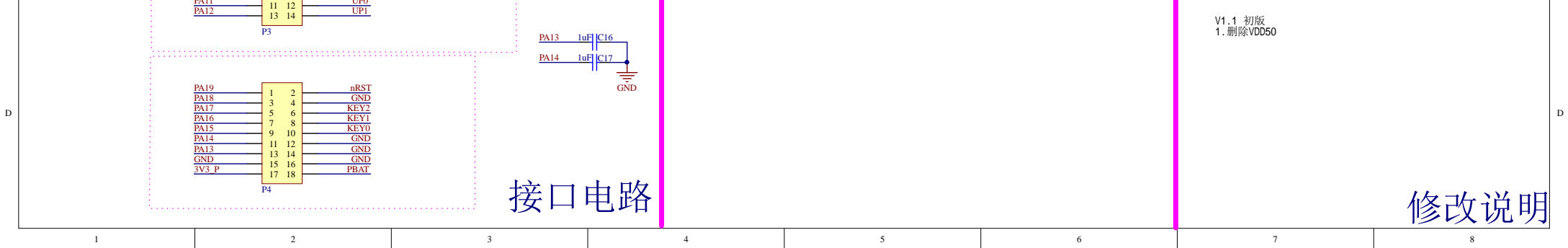
## 按键、灯



## 电源电路

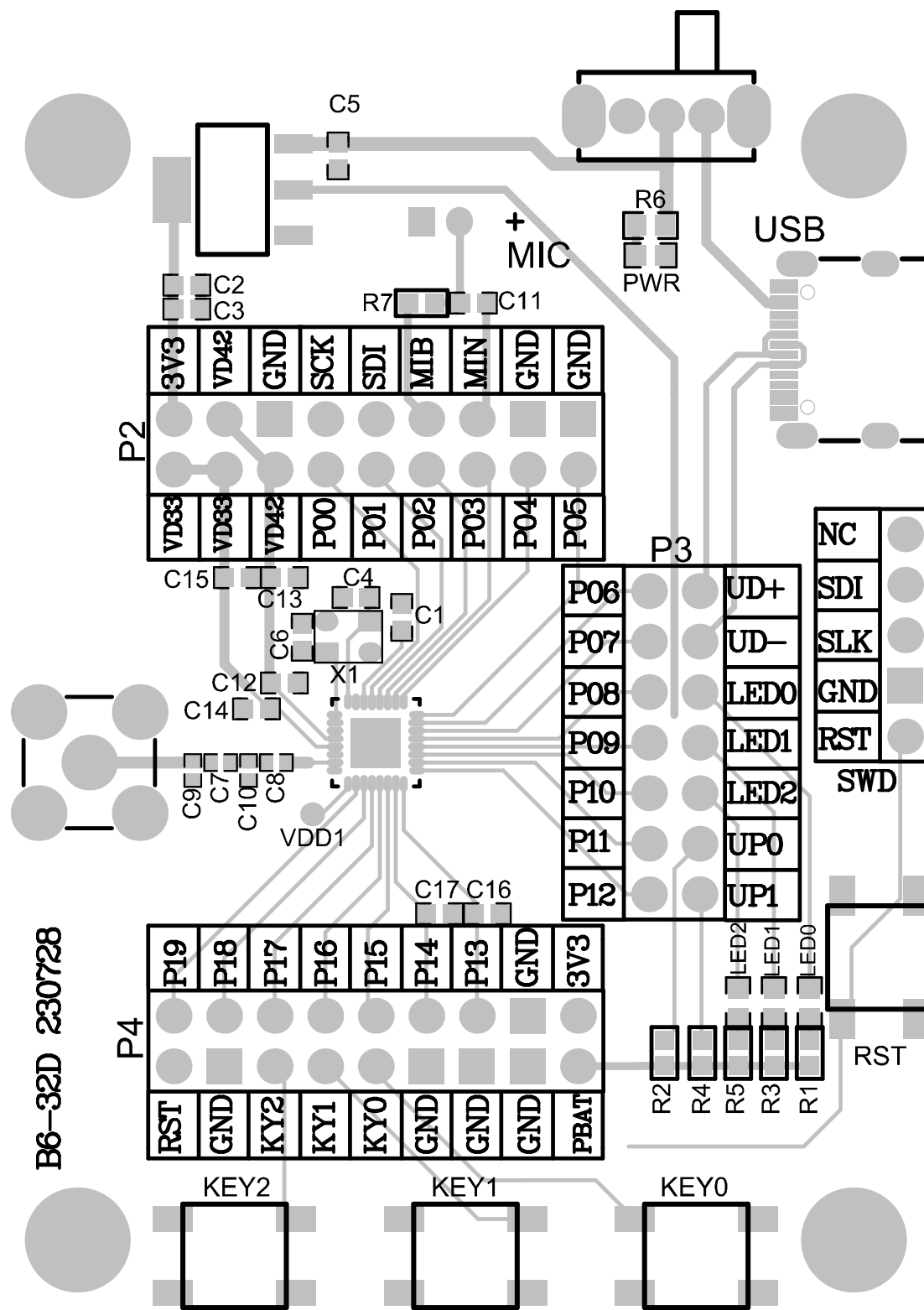


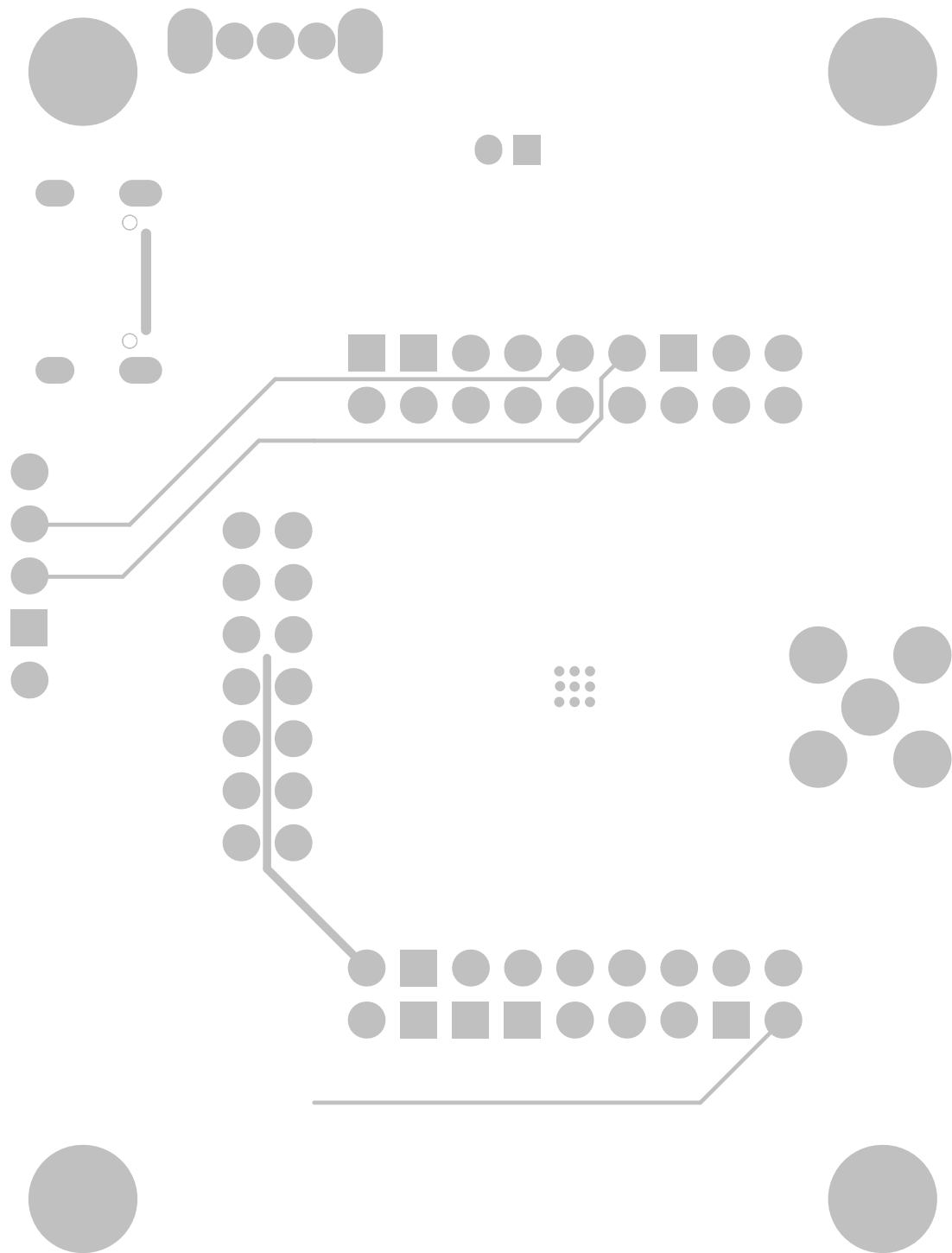
## MCU核



## 接口电路

## 修改说明





# Component list

Bill of Materials for Project [B6\_32D\_20230728.PrjPcb] (No PCB Document Selected)



Source Data From:

B6\_32D\_20230728.PrjPcb

Project:

B6\_32D\_20230728.PrjPcb

Variant:

None

Report Date:

2023/7/29

12:34

Print Date:

29-Jul-23

12:34:50 PM

#	Designator	LibRef	um Name Error:" Manufactu	Description	Footprint	Library Name	Comment	Quantity
1	C1, C4, C6	Cap		Capacitor (Semiconductor SIM Model)	C0603	HYBXX_Dragon.IntLib	NC	3
2	C2	Cap Pol3		Polarized Capacitor (Surface Mount)	C0603	HYBXX_Dragon.PcbLib	2.2uF	1
3	C3	Cap Pol3		Polarized Capacitor (Surface Mount)	C0603	HYBXX_Dragon.PcbLib	0.1uF	1
4	C5	Cap Pol3		Polarized Capacitor (Surface Mount)	C0603	HYBXX_Dragon.PcbLib	10uF	1
5	C7, C8, C9, C10	Cap		Capacitor (Semiconductor SIM Model)	C0402	HYBXX_Dragon.IntLib	0	4
6	C11, C16, C17	Cap		Capacitor (Semiconductor SIM Model)	C0603	HYBXX_Dragon.IntLib	1uF	3
7	C12, C14	Cap, Cap Semi		Capacitor (Semiconductor SIM Model)	C0603	HYBXX_Dragon.IntLib, Miscellaneous Devices.IntLib	100nF	2
8	C13, C15	Cap		Capacitor (Semiconductor SIM Model)	C0603	HYBXX_Dragon.IntLib	4.7uF	2
9	KEY0, KEY1, KEY2, RST	TSW SMD-6x6		贴片6x6轻触开关	SW-SMD	0.7 - 常用按键-开关.SchLib	6x6x5	4
10	LED0, LED1, LED2, PWR	LED		发光二极管	LED_0603	HYBXX_Dragon.IntLib		4
11	MIC	MIC1		电容麦克风	MIC-6*5.5mm	1.2 - 传感元件.SchLib	MIC-6*5mm	1
12	P1	SMA		SMA-2.4G射频天线接口	SMA-KE-LI	1.8 - WiFi天线-SMA射频座.SchLib	SMA	1
13	P2, P4	Header 9X2		9*2P接插件	HDR2.54-LI-2x9P	5.3 - 接插件-间距2.54 (100mil) .SchLib	Header 2X11	2
14	P3	Header 7X2		7*2P接插件	HDR2.54-LI-2x7P	5.3 - 接插件-间距2.54 (100mil) .SchLib	Header 2X7	1
15	R1, R3, R5	Res		贴片电阻	R 0603_L	HYBXX_Dragon.IntLib	3.3K	3
16	R2, R4	Res		贴片电阻	R 0603_L	HYBXX_Dragon.IntLib	5.1K	2
17	R6	Res		贴片电阻	RESC_0603	HYBXX_Dragon.IntLib	10k	1
18	R7	Res		贴片电阻	R 0603_L	HYBXX_Dragon.IntLib	2.2K	1
19	S1	SSW-1P		1路波动开关	SK12D07VG3	0.7 - 常用按键-开关.SchLib	SS-12F23	1
20	SP1, SP2, SP3, SP4	铜柱加头小焊盘		铜柱	M3x21+6 L	4.1 - 未分类器件.SchLib	M3铜柱	4
21	SWD1	Header 5		Header, 5-Pin	HDR2.54-LI-5P	5.3 - 接插件-间距2.54 (100mil) .SchLib	JLINK	1
22	U1	C1_QFN32		HY Dragon C 蓝牙芯片, QFN32_4x4	QFN32L_0404x0.75-0.40	HYBXX_Dragon.SchLib	C1_QFN32	1
23	USB	KH-TYPE-C-16P		连接器类型:Type-C;标准:-;公母:母座;触点数量:16;端口数量:1;安装方式:贴片;额定电流 - 电源:3A;工作温度范围:-40~+85;	USB-C-SMD_KH-TYPE-C-16P		KH-TYPE-C-16P	1
24	V1	AMS1117		LDO 可调节稳压芯片	SOT223_L	HYBXX_Dragon.SchLib		1
25	VDD1	HOLE		定位孔	TEST_PAD	HYBXX_Dragon.SchLib	HOLE	1
26	X1	XTAL-4P		4脚无源晶振	OSC3225-mini	2.0 - 保险丝-晶振-光耦.SchLib	16M	1
Approved			Notes					48

Project Full Path
Project Filename
Variant Name
Data-Source Filename
Data-Source Full Path
Title
Total Quantity
Report Time
Report Date
Report Date & Time
Output Name
Output Type
Output Generator Name
Output Generator Description

Z:\DragonC\PCBs\C1\QFN32\01Developmentboard\2023-07-28\B6\_32D\_20230728.PrjPcb

B6\_32D\_20230728.PrjPcb

None

B6\_32D\_20230728.PrjPcb

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Bill of Materials for Project [B6\_32D\_20230728.PrjPcb] (No PCB Document Selected)

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Bill of Materials

BOM\_PartType

BOM

Bill of Materials